

IN THE CLAIMS:

This listing of claims will replace all prior versions and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A microchip ~~for a personal computer~~, comprising:

a plurality of dies, at least two of the dies made by a separate fabrication process and assembled into a package with the separate die sections connected directly;

wherein at least one edge of at least one of the dies has any shape or pattern that is not a straight line.

~~a wireless network connection capable of coupling the personal computer to at least one other personal computer via a network;~~

~~a firewall comprising a hardware and/or a firmware component; and~~

~~a power management function component capable of managing power on the microchip.~~
 2. (Currently Amended) The microchip according to Claim 1, wherein the separate die sections are connected by at least one interconnect that is widened compared to the interconnect lines of the die.
 - 3 -20. (Deleted)
 21. (New) The microchip of Claim 1, wherein said at least one edge has a saw tooth pattern.
 22. (New) The microchip of Claim 21, wherein the saw tooth pattern is of two or more straight lines.

23. (New) The microchip of Claim 1, wherein said at least one edge has a pattern of straight lines in alternate directions.

24. (New) The microchip of Claim 23, wherein said at least one edge has a pattern of straight diagonal lines that alternate in direction.